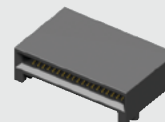


QSFP8-PF-02



QSFP8-038-01-L-D-RA1

(0.80 mm) .0315"

QSFP8, QSFP8-PF, QSFP8-PF SERIES

QSFP CONNECTOR & CAGE

SPECIFICATIONS

For complete specifications and recommended PCB layouts see www.samtec.com/QSFP8

Insulator Material:

LCP

Contact Material:

Phosphor Bronze

Ground Plane:

Phosphor Bronze

Plating:

Au or Sn over 50 μ " (1.27 μ m) Ni

Current Rating (QSFP8/Card):

1.6 A per pin

(2 pins powered)

RECOGNITIONS

For complete scope of recognitions see www.samtec.com/quality



Note:

Some lengths, styles and options are non-standard, non-returnable.

QSFP8

NO. OF
POSITIONSCARD
THICKNESS

PLATING

D

RA1

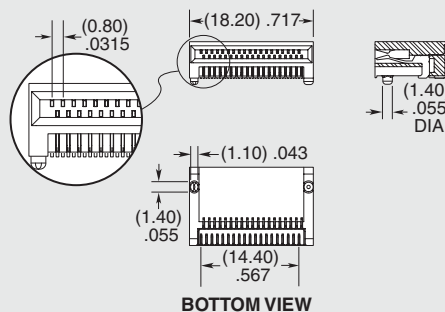
-038

= Total Number of Positions

-01

= (1.00 mm) .039"
thick card

-L

= 10 μ " (0.25 μ m) Gold on contact,
Matte Tin on tail

BOTTOM VIEW

SPECIFICATIONS

For complete specifications see www.samtec.com/QSFP8-PF or www.samtec.com/QSFP8-PF

TYPE

TERMINATION

OPTION

QSFP8

= Cage

QSFP8

= Cage and Connector Kit

-PF

= Press-fit

-01

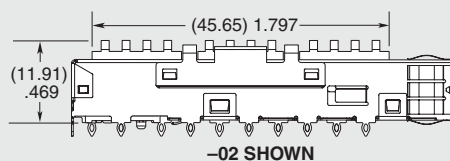
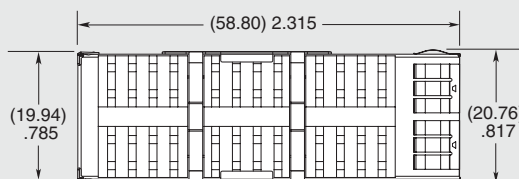
= Without Heat Sink

-02

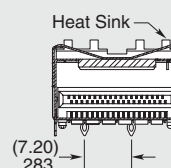
= With Heat Sink

-03

= With Heat Sink and
clip packaged separately
(Recommended for
cage press-fit processing)



-02 SHOWN



Note:

Some sizes, styles and options are non-standard, non-returnable.

Due to technical progress, all designs, specifications and components are subject to change without notice.

WWW.SAMTEC.COM

All parts within this catalog are built to Samtec's specifications.
Components must be approved by Samtec and identified in a Samtec customer-specific drawing to apply.